







BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



TO-220

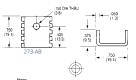
273 SERIES

LOW-COST, LOW-HEIGHT WAVE-SOLDERABLE **HEAT SINKS**

TO-220 and TO-218

| | Height Above | Footprint | | | | Thermal Performance at Typical Load | |
|------------|--------------|---------------------------|---------------|-------------|----------|-------------------------------------|-------------------|
| Standard | PC Board | Dimensions in. (mm) | Mounting | Solderable | Mounting | Natural | Forced |
| P/N | in. (mm) | | Configuration | Tab Options | Style | Convection | Convection |
| 273-AB | .375 (9.5) | .750 (19.1) x .750 (19.1) | Vertical | No Tab | Mtg Hole | 49°C @ 2W | 7.2°C/W @ 400 LFM |
| 273-ABE-01 | .375 (9.5) | .750 (19.1) x .750 (19.1) | | 01 | Mtg Hole | 49°C @ 2W | 7.2°C/W @ 400 LFM |
| 273-ABE-02 | .375 (9.5) | .750 (19.1) x .750 (19.1) | | 02 | Mtg Hole | 49°C @ 2W | 7.2°C/W @ 400 LFM |

MECHANICAL DIMENSIONS







NATURAL AND FORCED **CONVECTION CHARACTERISTICS**

Note: 1. Suggested Tab Hole = e.075 (1.9) (Plated) with e.100 (2.5) pad

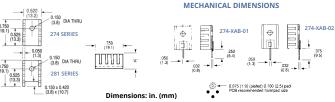
LOW-COST, LOW-HEIGHT WAVE-SOLDERABLE **HEAT SINKS**

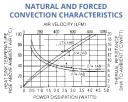
274 & 281 SERIES



| He | eight Above | Footprint | | | | Thermal Performance at Typical Load | |
|---|---|---|--|--|--|--|--|
| | PC Board in. (mm) | Dimensions in. (mm) | Mounting Configuration | Solderable Tab Options | Mounting Style | Natural Convection | Forced Convection |
| 274-1ABE-01 274-1ABE-02 274-2AB 274-2ABE-01 274-2ABE-02 274-3AB 274-3ABE-01 274-3ABE-02 281-1AB | .375 (9.5) .375 (9.5) .375 (9.5) .500 (12.7) .500 (12.7) .250 (6.4) .250 (6.4) .250 (6.4) .375 (9.5) .500 (12.7) | .520 (13.2) x .750 (19.1) 520 (13.2) x .750 (19.1) | Vert./Horiz. Vertical Vertical Vert./Horiz. Vertical Vert./Horiz. Vertical Vertical Vertical Vertical Vertical Vertical Vertical Vertical Vertical | No Tab 01 02 No Tab 01 02 No Tab 01 02 No Tab No Tab | Mtg Hole Mtg Hole | 56° C @ 2W 56° C @ 2W 50° C @ 2W 50° C @ 2W 50° C @ 2W 62° C @ 2W 62° C @ 2W 62° C @ 2W 56° C @ 2W 50° C @ 2W | 8.0°C/W @ 400 LFM 8.0°C/W @ 400 LFM 7.0°C/W @ 400 LFM 7.0°C/W @ 400 LFM 7.0°C/W @ 400 LFM 9.0°C/W @ 400 LFM 9.0°C/W @ 400 LFM 9.0°C/W @ 400 LFM 8.0°C/W @ 400 LFM 7.0°C/W @ 400 LFM |

Material: Aluminum, Black Anodized





TO-220

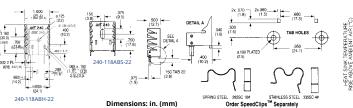
LABOR-SAVING TWISTED FIN HEAT SINKS

240 SERIES

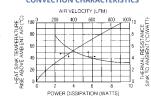


| | Height Above Footprint | | | | | Thermal Performance at Typical Load | |
|------------------------------------|------------------------|--|---------------------------|---------------------------|--------------------------------|-------------------------------------|--|
| Standard P/N | PC Board in. (mm) | Dimensions in. (mm) | Mounting Configuration | Solderable Tab Options | Mounting Style | Natural Convection | Forced Convection |
| 240-118ABEH-22 240-118ABES-22 | | 1.000 (25.4) x .500 (12.7) 1.000 (25.4) x .500 (12.7) | | 22 22 | Clip/Mtg Hole Clip/Mtg Slot | | 5.3°C/W @ 400 LFM 5.3°C/W @ 400 LFM |
| Material: Aluminum, Black Anodized | | | | | | | |

MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



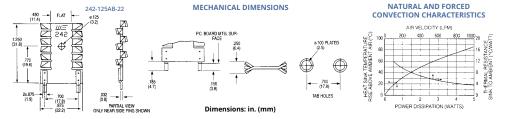


242 SERIES

LOW-COST, LOW-HEIGHT WAVE-SOLDERABLE HEAT SINKS

TO-220

| | Height Above Footprint | | | | | Thermal Performance at Typical Load | | |
|------------------------------------|------------------------|--------------------------|---------------------------|---------------------------|-------------------|-------------------------------------|----------------------|--|
| Standard P/N | PC Board in. (mm) | Dimensions in. (mm) | Mounting Configuration | Solderable Tab Options | Mounting Style | Natural Convection | Forced Convection | |
| 242-125ABE-22 | 1.285 (32.6) | .875 (22.2) x .250 (6.4) | Vertical | 22 | Mtg Hole | 48°C @ 2W | 6.2°C/W @ 400 LFM | |
| Material: Aluminum, Black Anodized | | | | | | | | |



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